

3N Copper Wire with Trace Additions for Bonding in Microelectronics Device

5

ABSTRACT

A 3N copper wire with trace additions for bonding in microelectronics comprising one or more of a group of Ag, Ni, Pd, Au, Pt, and Cr as corrosion resistance addition material, wherein a concentration of said corrosion resistance addition material is
10 between about 90wt.ppm to about 980wt.ppm.

FIG. 1

15